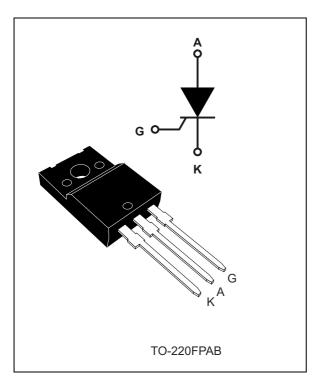


# TN2015H-6FP

### High temperature 20 A SCRs

Datasheet – production data



### Features

- High junction temperature: T<sub>i</sub> = 150 °C
- High noise immunity dV/dt = 750 V/µs up to 150 °C
- Gate triggering current I<sub>GT</sub> = 15 mA
- Blocking voltage V<sub>DRM</sub>/V<sub>RRM</sub> = 600 V
- High turn on current rise dl/dt: 100 A/µs
- ECOPACK<sup>®</sup>2 compliant component
- Complies with UL standards (File ref: E81734)
- Insulated package TO-220FPAB:
  - Insulated voltage: 2000 VRMS

### **Applications**

- Voltage regulator circuits for motorbikes
- Inrush current limiting circuits
- Motor control circuits and starters
- Light dimmers
- Solid state relays

### Description

Thanks to a junction temperature  $T_j$  up to 150 °C and an insulated TO-220FPAB package, the TN2015H-6FP offers high thermal performance operation up to 20 A rms.

The trade-off between the device's noise immunity (dV/dt = 750 V/ $\mu$ s), its gate triggering current (I<sub>GT</sub> = 15 mA) and its turn-on current rise (dI/dt = 100 A/ $\mu$ s) allows the design of robust and compact control circuits for voltage regulators in motorbikes and industrial drives, overvoltage crowbar protection, motor control circuits in power tools and kitchen aids, inrush current limiting circuits.

The insulated fullpack package allows a back-to-back configuration.

Table 1. Device summary

Order code	Package	V <sub>DRM</sub> /V <sub>RRM</sub>	I <sub>GT</sub>
TN2015H-6FP	TO-220FPAB	600 V	15 mA

This is information on a product in full production.

## 1 Characteristics

Symbol	Parameter			Value	Unit
I <sub>T(RMS)</sub>	On-state rms current (180° conduction a	ngle)	T <sub>c</sub> = 80 °C	20	А
			T <sub>c</sub> = 80 °C	12.7	
I <sub>T(AV)</sub>	Average on-state current (180° conduction	on angle)	T <sub>c</sub> = 99 °C	10	А
			T <sub>c</sub> = 112 °C	8	
			t = 8.3 ms	197	А
I <sub>TSM</sub>			t = 10 ms	180	A
l²t	$I^{2}t$ value for fusing (T <sub>j</sub> initial = 25 °C) $t_{p} = 10 \text{ ms}$		t <sub>p</sub> = 10 ms	162	A <sup>2</sup> s
dl/dt	$ \begin{array}{l} \mbox{Critical rate of rise of on-state current} \\ \mbox{I}_G = 2 \ x \ \mbox{I}_{GT}, \ \mbox{t}_r \leq 100 \ \mbox{ns}, \ \mbox{T}_j = 25 \ \ \mbox{°C} \end{array} \end{array} \ F = 60 \ \mbox{Hz} \label{eq:F} $		100	A/µs	
V <sub>DRM</sub> , V <sub>RRM</sub>	Repetitive peak off-state voltage		600	V	
I <sub>GM</sub>	Peak gate current	t <sub>p</sub> = 20 μs	T <sub>j</sub> = 150 °C	4	А
P <sub>G(AV)</sub>	Average gate power dissipation $T_j = 150 \text{ °C}$		1	W	
T <sub>stg</sub> T <sub>j</sub>	Storage junction temperature range Operating junction temperature range		- 40 to + 150 - 40 to + 150	°C	
ΤL	Maximum lead temperature for soldering during 10 s		260	°C	
V <sub>ins</sub>	Insulation rms voltage, 1 minute		TO-220FPAB	2000	V

### Table 3. Electrical characteristics ( $T_j = 25$ °C, unless otherwise specified)

Symbol	Test conditions			Value	Unit
	V = 12 V P = 22 O		Тур.	6	mA
'GT	$I_{GT}$ $V_D = 12 V, R_L = 33 \Omega$		Max.	15	
V <sub>GT</sub>	$V_D$ = 12 V, $R_L$ = 33 $\Omega$		Max.	1.3	V
V <sub>GD</sub>	$V_{D} = V_{DRM}, R_{L} = 3.3 \text{ k}\Omega \qquad \qquad T_{j} = 150 \text{ °C}$		Min.	0.2	V
Ι <sub>Η</sub>	I <sub>T</sub> = 500 mA, gate open		Max.	50	mA
١L	$I_G = 1.2 \times I_{GT}$		Max.	60	mA
dV/dt	$V_D$ = 402 V, gate open $T_j$ = 150 °C		Min.	750	V/µs
t <sub>gt</sub>	$I_{T} = 40 \text{ A},  V_{D} = 600 \text{ V},  I_{G} = 100 \text{ mA}, \\ (\text{d}I_{G}/\text{d}t)\text{max} = 0.2  \text{A}/\mu\text{s}$		Тур	1.9	μs
tq		T <sub>j</sub> = 150 °C	Тур	70	μs



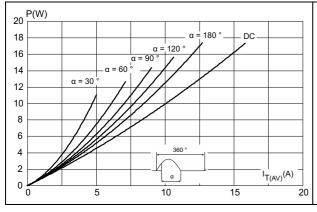
Symbol	Test conditions			Value	Unit
V <sub>TM</sub>	I <sub>TM</sub> = 40 A, t <sub>p</sub> = 380 μs	T <sub>j</sub> = 25 °C	Max.	1.6	V
V <sub>t0</sub>	Threshold voltage	T <sub>j</sub> = 150 °C	Max.	0.82	V
R <sub>d</sub>	Dynamic resistance	T <sub>j</sub> = 150 °C	Max.	17.5	mΩ
I <sub>DRM,</sub>		T <sub>j</sub> = 25 °C	Max.	5	μA
I <sub>RRM</sub>	$V_{D} = V_{DRM}, V_{R} = V_{RRM}$	T <sub>j</sub> = 150 °C	ividX.	2	mA

#### Table 4. Static characteristics

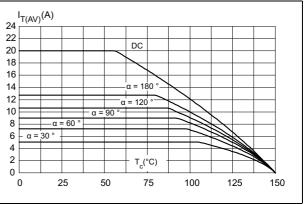
#### Table 5. Thermal resistance

Symbol	Parameter	Value	Unit
R <sub>th(j-c)</sub>	Junction to case (AC)	4.0	°C/W
R <sub>th(j-a)</sub>	Junction to ambient (DC)	60	°C/W

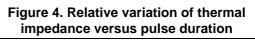
# Figure 1. Maximum power dissipation versus average on-state current



# Figure 2. Average and DC on-state current versus case temperature



# Figure 3. Average and DC on-state current versus ambient temperature



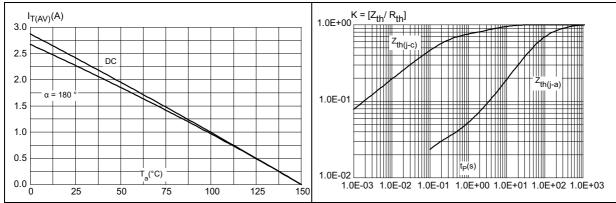
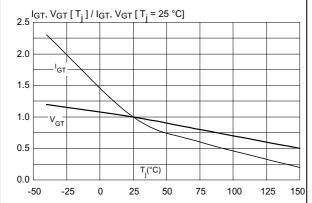
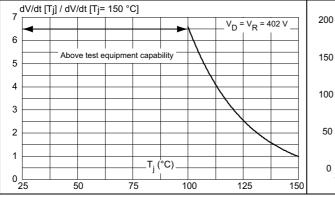




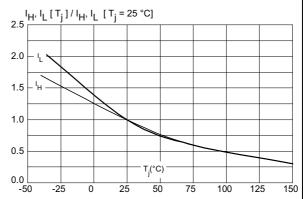
Figure 5. Relative variation of gate triggering current and gate voltage versus junction temperature (typical values)

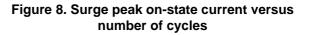


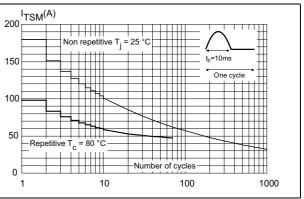
#### Figure 7. Relative variation of static dV/dt immunity versus junction temperature (typical values)



#### Figure 6. Relative variation of holding current and latching current versus junction temperature (typical values)

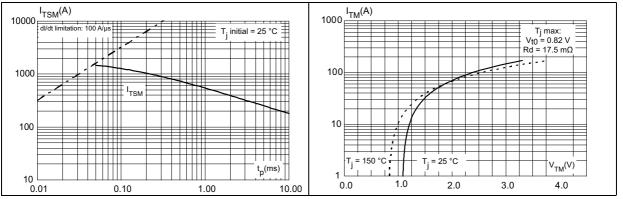




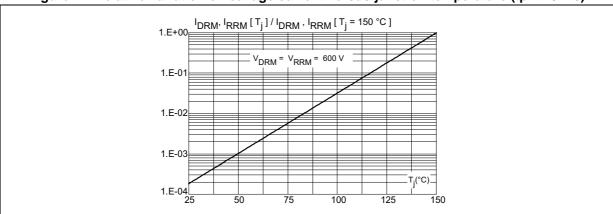


# Figure 9. Non-repetitive surge peak on-state current for a sinusoidal pulse (tp < 10 ms)

## Figure 10. On-state characteristics (maximum values)







#### Figure 11. Relative variation of leakage current versus junction temperature (tp < 10 ms)



### 2 Package information

- Epoxy meets UL94, V0
- Lead-free package
- Halogen free molding compound
- Recommended torque: 0.4 to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.

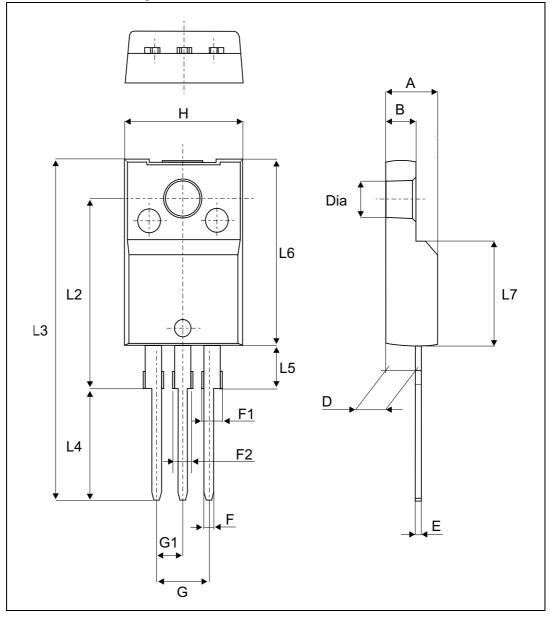


Figure 12. TO-220FPAB dimension definitions

	Dimensions				
Ref.	Millim	eters	Incl	hes	
	Min.	Max.	Min.	Max.	
А	4.4	4.6	0.173	0.181	
В	2.5	2.7	0.098	0.106	
D	2.5	2.75	0.098	0.108	
E	0.45	0.70	0.018	0.027	
F	0.75	1	0.030	0.039	
F1	1.15	1.70	0.045	0.067	
F2	1.15	1.70	0.045	0.067	
G	4.95	5.20	5.20 0.195		
G1	2.4	2.7	0.094 0.1		
Н	10	10.4	0.393 0.409		
L2	16 7	ур.	0.63 Тур.		
L3	28.6	30.6	1.126	1.205	
L4	9.8	10.6	0.386	0.417	
L5	2.9	3.6	0.114 0.		
L6	15.9	16.4	0.626 0.6		
L7	9.00	9.30	0.354	0.366	
Dia.	3.00	3.20	0.118	0.126	

Table 6. TO-220FPAB dimensions



## **3** Ordering information

T = TO-220FPAB Delivery mode Blank = tube

#### Figure 13. Ordering information scheme

#### Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
TN2015H-6FP	TN2015H6	TO-220FPAB	2.0 g	50	Tube

## 4 Revision history

Table 8. Document revision I	historv
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Date	Revision	Changes
25-Feb-2015	1	Initial release.



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